

Diode

Emitter Controlled 4 Medium Power Technology
IDC73D120T8M

Data Sheet

Industrial Power Control



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Diode Chip in Emitter Controlled 4 Medium Power Technology

Features:

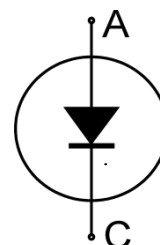
- 1200V Emitter Controlled 4 technology
110µm chip
- Soft, fast switching
- Low reverse recovery charge
- Small temperature coefficient

Recommended for:

- Low / medium power modules

Applications:

- Low / medium power drives



Chip Type	V_R	I_{FN}	Die Size	Package
IDC73D120T8M	1200V	150A	9.00mm x 8.15mm	Sawn on foil

Mechanical Parameters

Die size	9.00 x 8.15	mm ²
Area total	73.35	
Anode pad size	8.026 x 7.196	
Silicon thickness	110	µm
Wafer size	200	mm
Maximum possible chips per wafer	358	
Passivation frontside	Photoimide	
Pad metal	3200nm AlSiCu	
Backside metal	Ni Ag – system To achieve a reliable solder connection it is strongly recommended not to consume the Ni layer completely during production process	
Die bond	Electrically conductive epoxy glue and soft solder	
Wire bond	Al, ≤500µm	
Reject ink dot size	∅ 0.65mm; max 1.2mm	
Storage environment (<6 months)	for original and sealed MBB bags	Ambient atmosphere air, temperature 17°C – 25°C
	for open MBB bags	Acc. IEC 62258-3; Section 9.4 Storage Environment.

Maximum Ratings

In general, from reliability and lifetime point of view, the lower the operation junction temperature and/or the applied voltage, the greater the expected lifetime of any semiconductor device.

Parameter	Symbol	Conditions	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	$T_{vj}=25^{\circ}C$	1200	V
Continuous forward current ¹	I_F		-	A
Maximum repetitive forward current ²	I_{FRM}		300	
Junction temperature	T_{vj}		-40...+175	$^{\circ}C$
Operating junction temperature	$T_{vj\ op}$		-40...+150	$^{\circ}C$

Static Characteristics (tested on wafer), $T_{vj}=25^{\circ}C$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Reverse leakage current	I_R	$V_R=1200V$	-	-	26	μA
Cathode-anode breakdown voltage	V_{BR}	$I_R=0.25mA$	1200	-	-	V
Forward voltage drop	V_F	$I_F=45A$	1.03	1.25	1.37	

Electrical Characteristics ²

Parameter	Symbol	Conditions	Value			Unit	
			min.	typ.	max.		
Forward voltage drop	V_F	$I_F=150A$	$T_{vj}=25^{\circ}C$	1.35	1.70	2.05	V
			$T_{vj}=150^{\circ}C$	-	1.65	-	

Further Electrical Characteristics

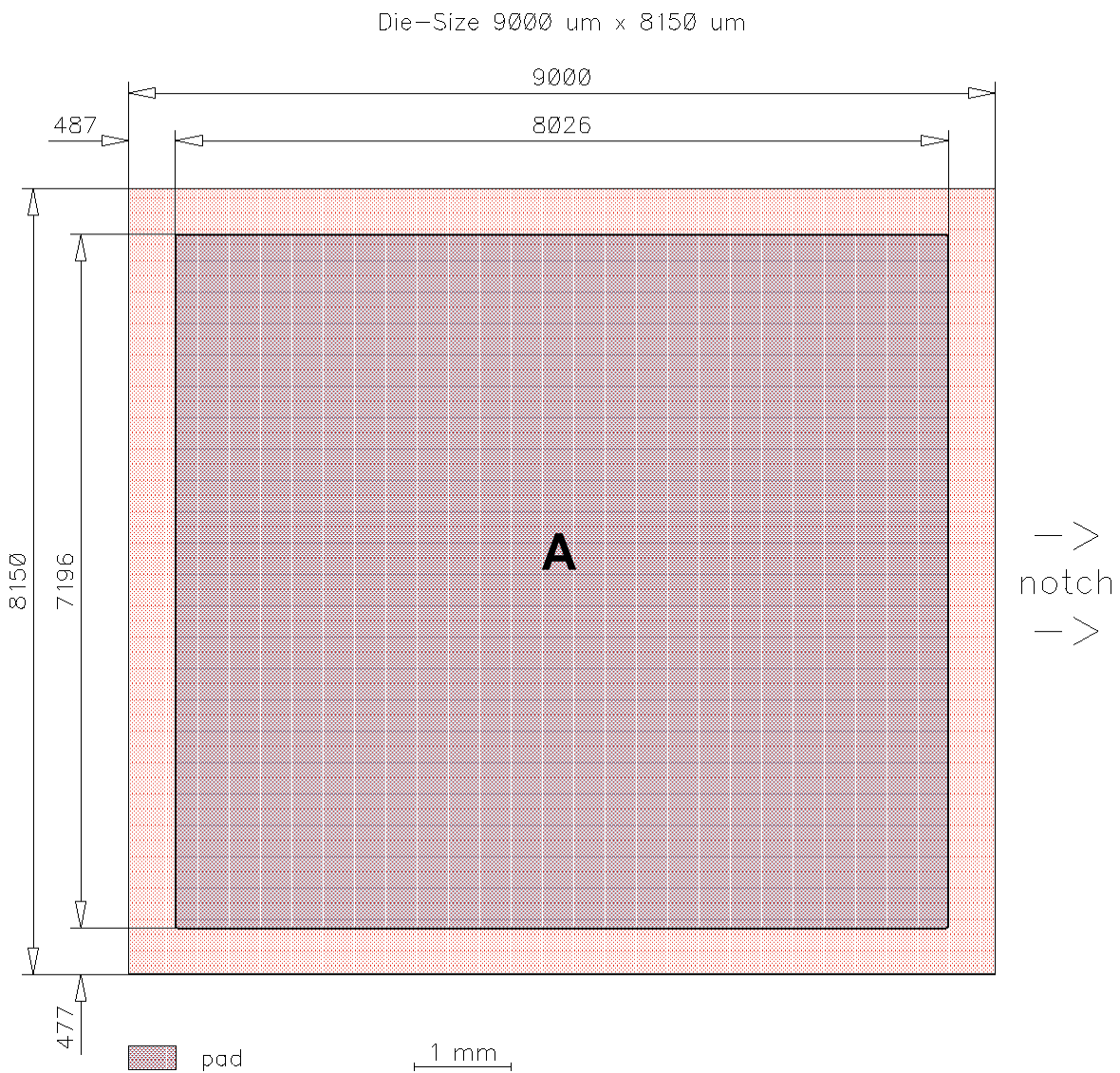
Switching characteristics and thermal properties are depending strongly on module design and mounting technology and can therefore not be specified for a bare die.

Application example	FS150R12KT4	Rev. 2.1
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¹ Depending on thermal properties of assembly.

² Not subject to production test - verified by design/characterization.

Chip Drawing



A = Anode pad



IDC73D120T8M

Bare Die Product Specifics

Test coverage at wafer level cannot cover all application conditions. Therefore it is recommended to test all characteristics which are relevant for the application at package level, including RBSOA and SCSOA.

Description

AQL 0.65 for visual inspection according to failure catalogue

Electrostatic Discharge Sensitive Device according to MIL-STD 883

Revision History

Revision	Subjects (major changes since last revision)	Date
2.0	Final data sheet	22.08.2016

Relevant Application Notes



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